


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM8S207R616 STM8S207R616TR	U25W*765XXXV	A	959	20-04-2018
Amount	UoM	Unit type	ST ECOPACK Grade	
350.00	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	U25W*765XXXV				6000000.0	999998.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.683	mg	supplier	die	Silicon (Si)	7440-21-3		6.477	mg	969176	18506
				supplier	metallization	Aluminium (Al)	7429-90-5		0.018	mg	2693	51
				supplier	metallization	Copper (Cu)	7440-50-8		0.060	mg	8978	171
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.007	mg	1047	20
				supplier	metallization	Titanium (Ti)	7440-32-6		0.009	mg	1347	26
				supplier	Passivation	Silicon Nitride	12033-89-5		0.016	mg	2394	46
				supplier	Passivation	Silicon Oxide	7631-86-9		0.096	mg	14365	274
Lead-frame	M-011 Other inorganic materials	95.854	mg	supplier	alloy	Copper (Cu)	7440-50-8		91.280	mg	952284	260799
				supplier	alloy	Nickel (Ni)	7440-02-0		2.847	mg	29697	8133
				supplier	alloy	Silicium (Si)	7440-21-3		0.617	mg	6434	1762
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.142	mg	1485	407
				supplier	coating	Nickel (Ni)	7440-02-0		0.888	mg	9259	2536
				supplier	coating	Palladium (Pd)	7440-05-3		0.057	mg	593	162
				supplier	coating	Gold (Au)	7440-57-5		0.024	mg	247	68
Die Attach	M-011 Other inorganic materials	3.074	mg	supplier	glue or soft solder	Silver (Ag)	7440-22-4		2.367	mg	770000	6763
				supplier	glue or soft solder	Epoxy Cresol Novolak	29690-82-2		0.695	mg	226000	1985
				supplier	glue or soft solder	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.012	mg	4000	35
Wires	M-011 Other inorganic materials	1.084	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		1.084	mg	1000000	3098
Encapsulation	M-011 Other inorganic materials	243.298	mg	supplier	Moulding Compound	Silica, vitreous	60676-86-0		213.042	mg	875641	608691
				supplier	Moulding Compound	Epoxy resin	Proprietary		17.456	mg	71746	49873
				supplier	Moulding Compound	Phenol resin	Proprietary		12.103	mg	49744	34579
Finishing	M-011 Other inorganic materials	0.007	mg	supplier	Moulding Compound	Carbon Black	1333-86-4		0.698	mg	2870	1995
				supplier	connections coating	Nickel (Ni)	7440-02-0		0.006	mg	916800	17
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	58700	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	24500	0